

## N-Channel Enhancement Mode MOSFET

### 1. Product Information

#### 1.1 Features

- Advanced trench cell design
- Low Thermal Resistance

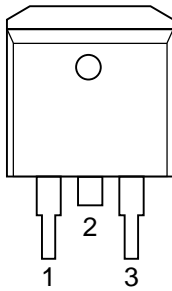
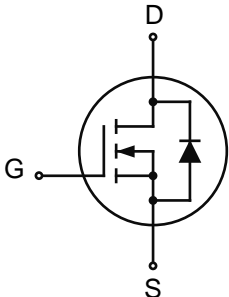
#### 1.2 Applications

- Motor drivers
- DC/DC Converter

#### 1.3 Quick reference

- $BV \geq 120\text{ V}$
- $R_{DS(ON)} \leq 6.0\text{ m}\Omega @ V_{GS} = 10\text{ V}$
- $P_{tot} \leq 147\text{ W}$
- $R_{DS(ON)} \leq 8.0\text{ m}\Omega @ V_{GS} = 6\text{ V}$
- $I_D \leq 100\text{ A}$

### 2. Pin Description

Pin	Description	Simplified Outline	Symbol
1	Gate(G)	 <p>Top View TO-263</p>	
2	Drain(D)		
3	Source(S)		

## 3. Limiting Values

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{DS}$	Drain-Source Voltage	$T_C=25^{\circ}C$	120	-	V
$V_{GS}$	Gate-Source Voltage	$T_C=25^{\circ}C$	-	$\pm 20$	V
$I_D^*$	Drain Current (DC)	$T_C=25^{\circ}C, V_{GS}=10\text{ V}$	-	100	A
		$T_C=100^{\circ}C, V_{GS}=10\text{ V}$	-	63	A
$I_{DM}^{*,**,***}$	Drain Current (Pulsed)	$T_C=25^{\circ}C, V_{GS}=10\text{ V}$	-	240	A
$P_{tot}$	Total Power Dissipation	$T_C=25^{\circ}C$	-	147	W
$T_{stg}$	Storage Temperature		-55	150	$^{\circ}C$
$T_J$	Junction Temperature		-	150	$^{\circ}C$
$I_S$	Diode Forward Current	$T_C=25^{\circ}C$	-	100	A
$E_{AS}^*$	Single Pulsed Avalanche Energy	$V_{DD}=50\text{ V}, L=1.0\text{ mH}$	-	800	mJ
$R_{\theta JA}^*$	Thermal Resistance-Junction to Ambient		-	62.5	$^{\circ}C/W$
$R_{\theta JC}^*$	Thermal Resistance-Junction to Case		-	0.85	

Notes:

- \* Surface Mounted on 1 in<sup>2</sup> pad area,  $t \leq 10\text{ sec}$
- \*\* Pulse width  $\leq 300\ \mu\text{s}$ , duty cycle  $\leq 2\%$
- \*\*\* Limited by bonding wire

## 4. Marking Information

Product Name	Marking
KJ0512DH	<div style="display: inline-block; background-color: black; color: white; padding: 2px;">0512H YWWXXX</div> YWW: Date Code

## 5. Ordering Code

Product Name	Package	Reel Size	Tape width	Quantity	Note
KJ0512DH	TO-263			800	

Note: KUIJIEXIN defines "Green" as lead-free (RoHS compliant) and halogen free (Br or Cl does not exceed 900 ppm by weight in homogeneous material and total of Br and Cl does not exceed 1500 ppm by weight; Follow IEC 61249-2-21 and IPC/JEDEC J-STD-020C)

## 6. Electrical Characteristics (T<sub>A</sub> = 25°C Unless Otherwise Noted)

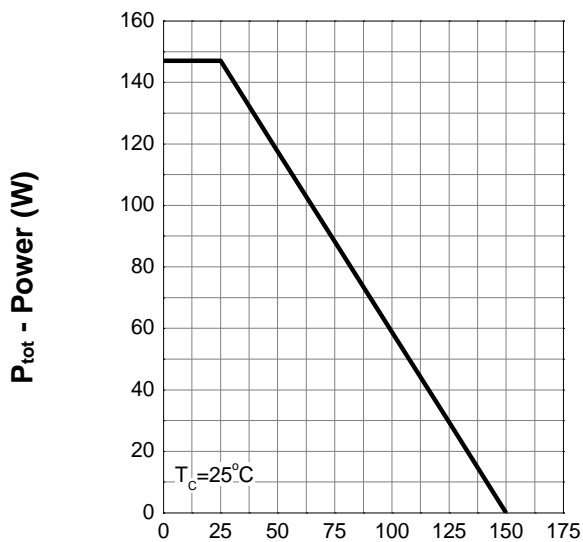
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Static Characteristics</b>						
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0 V, I <sub>D</sub> =250 μA	120	-	-	V
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>DS</sub> =250 μA	2	-	4	V
I <sub>DSS</sub>	Zero Gate Voltage Source Current	V <sub>DS</sub> =96 V, V <sub>GS</sub> =0 V	-	-	1	μA
I <sub>GSS</sub>	Gate Leakage Current	V <sub>GS</sub> =±20 V, V <sub>DS</sub> =0 V	-	-	± 100	nA
R <sub>DS(ON)</sub> <sup>a</sup>	Drain-Source On-State Resistance	V <sub>GS</sub> =10 V, I <sub>D</sub> =50 A	-	5.5	6.0	mΩ
	Drain-Source On-State Resistance	V <sub>GS</sub> =6 V, I <sub>D</sub> =30 A	-	6.9	8.0	mΩ
<b>Diode Characteristics</b>						
V <sub>SD</sub> <sup>a</sup>	Diode Forward Voltage	I <sub>SD</sub> =50 A, V <sub>GS</sub> =0 V	-	-	1.3	V
t <sub>rr</sub>	Reverse Recovery Time	I <sub>SD</sub> =50 A, dI <sub>SD</sub> /dt=100 A/μs	-	100	-	ns
Q <sub>rr</sub>	Reverse Recovery Charge		-	307	-	nC
<b>Dynamic Characteristics<sup>b</sup></b>						
C <sub>iss</sub>	Input Capacitance	V <sub>GS</sub> =0 V, V <sub>DS</sub> =60 V Frequency=1 MHz	-	4903	-	pF
C <sub>oss</sub>	Output Capacitance		-	566	-	
C <sub>rss</sub>	Reverse Transfer Capacitance		-	47	-	
t <sub>d(on)</sub>	Turn-on Delay Time	V <sub>DS</sub> =60 V, V <sub>GEN</sub> =10 V, R <sub>G</sub> =3.9 Ω, R <sub>L</sub> =1.2 Ω, I <sub>D</sub> =50 A	-	18	-	ns
t <sub>r</sub>	Turn-on Rise Time		-	71	-	
t <sub>d(off)</sub>	Turn-off Delay Time		-	51	-	
t <sub>f</sub>	Turn-off Fall Time		-	79	-	
<b>Gate Charge Characteristics<sup>b</sup></b>						
Q <sub>g</sub>	Total Gate Charge	V <sub>GS</sub> =10 V, V <sub>DS</sub> =60 V, I <sub>DS</sub> =50 A	-	81	-	nC
Q <sub>gs</sub>	Gate-Source Charge		-	28	-	
Q <sub>gd</sub>	Gate-Drain Charge		-	18	-	

Notes:

- Pulse test; pulse width ≤ 300 μs, duty cycle ≤ 2%
- Guaranteed by design, not subject to production testing

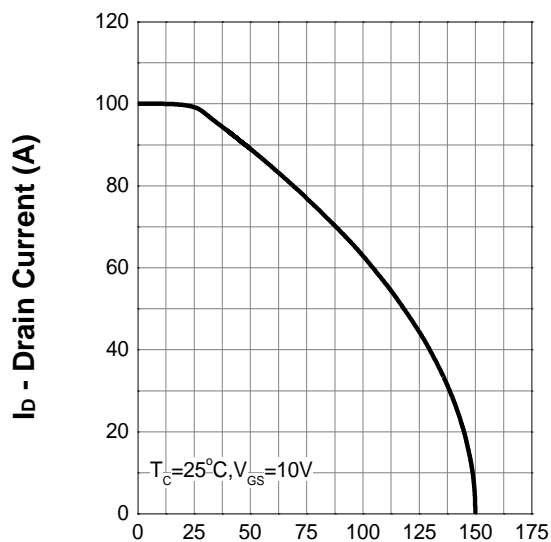
## 7. Typical Characteristics

### Power Capability



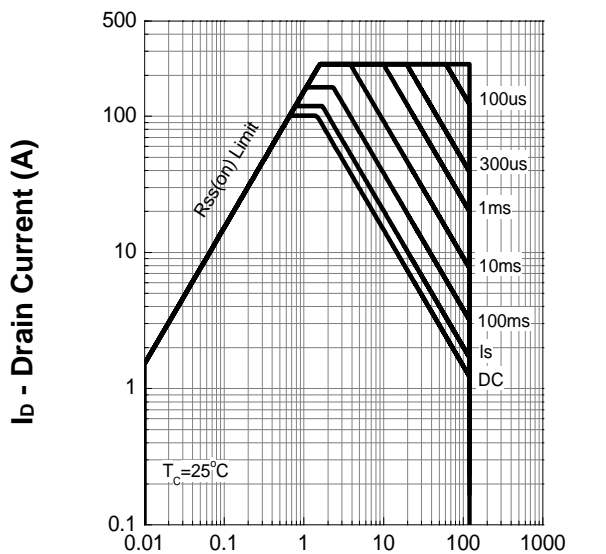
T<sub>j</sub> - Junction Temperature (°C)

### Current Capability



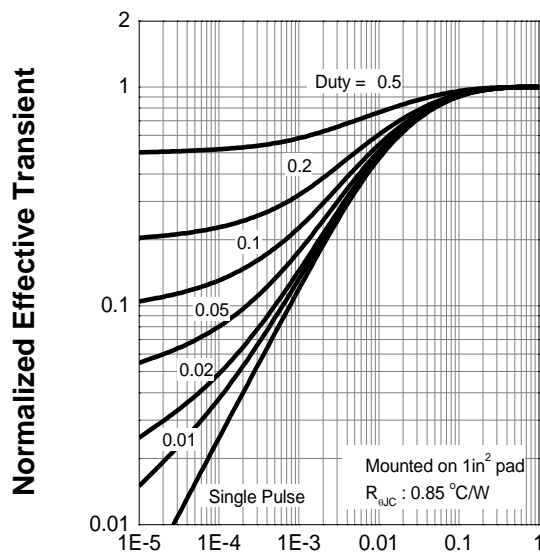
T<sub>j</sub> - Junction Temperature (°C)

### Safe Operation Area



V<sub>DS</sub> - Drain-Source Voltage (V)

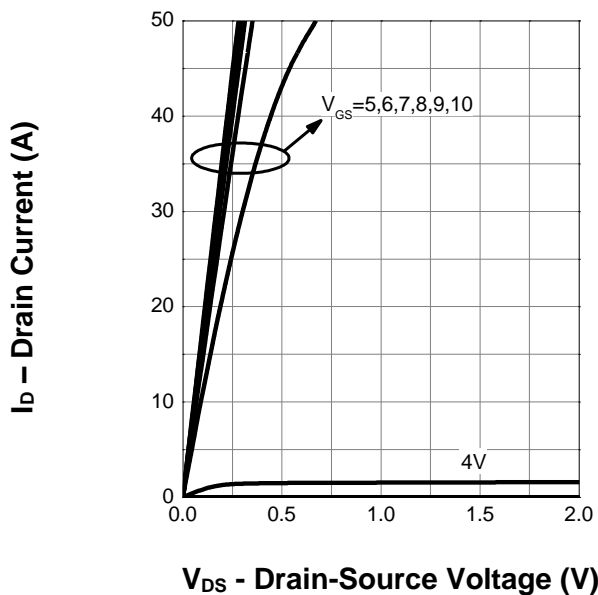
### Thermal Transient Impedance



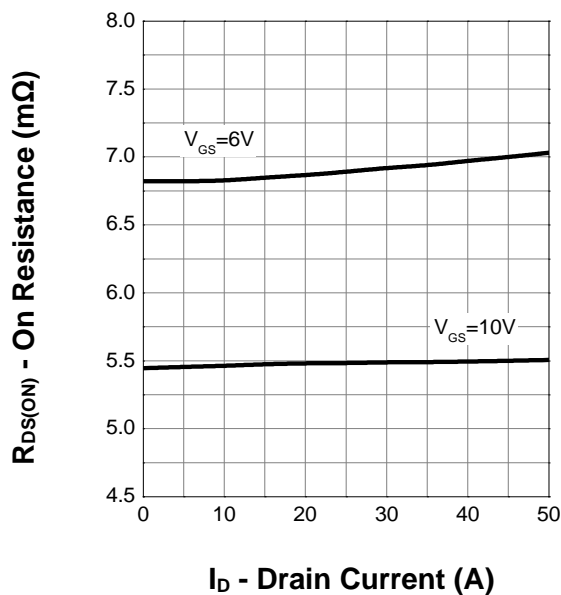
Square Wave Pulse Duration (sec)

## 7. Typical Characteristics (cont.)

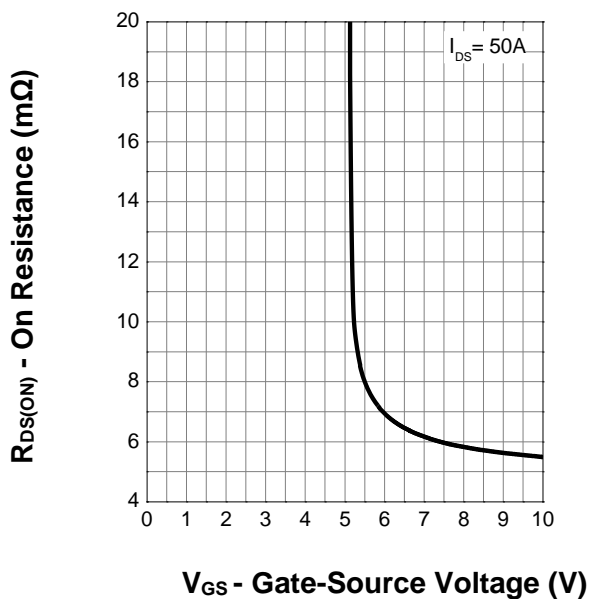
**Output Characteristics**



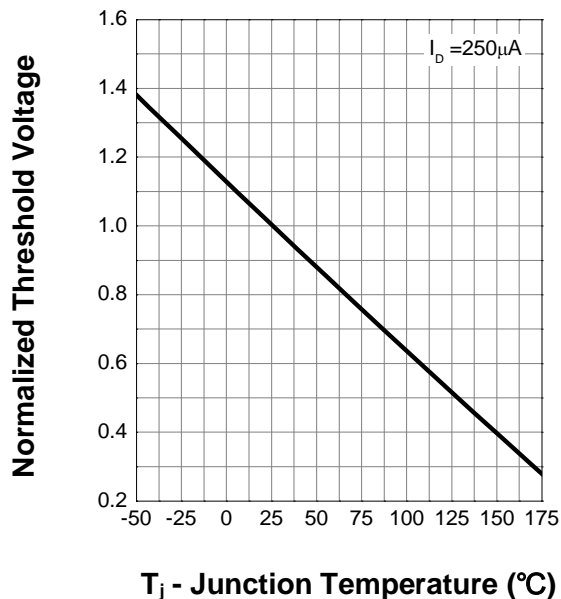
**Drain-Source On Resistance**



**Transfer Characteristics**

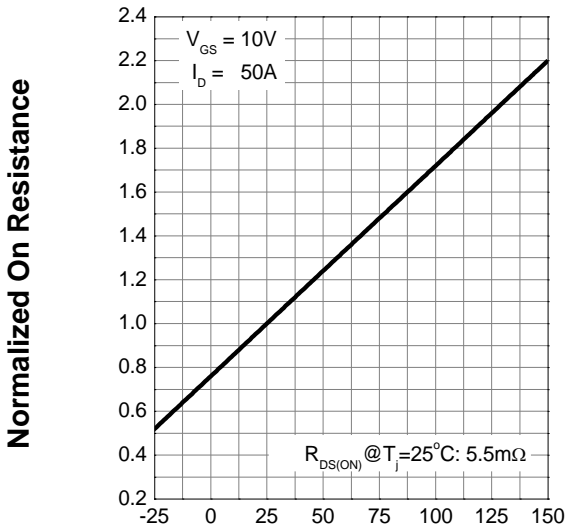


**Gate Threshold Voltage**

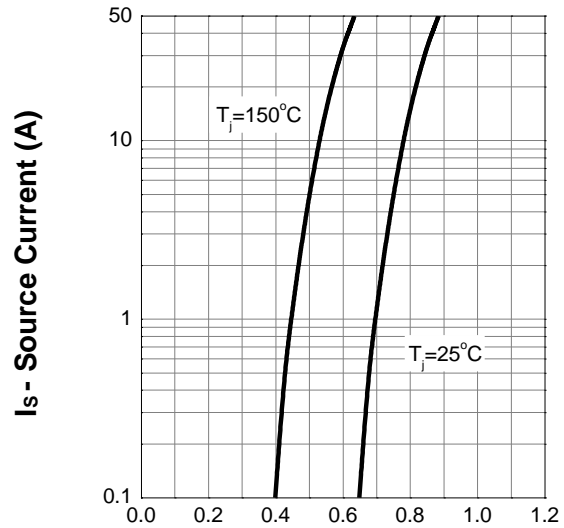


## 7. Typical Characteristics (cont.)

### Drain-Source On Resistance



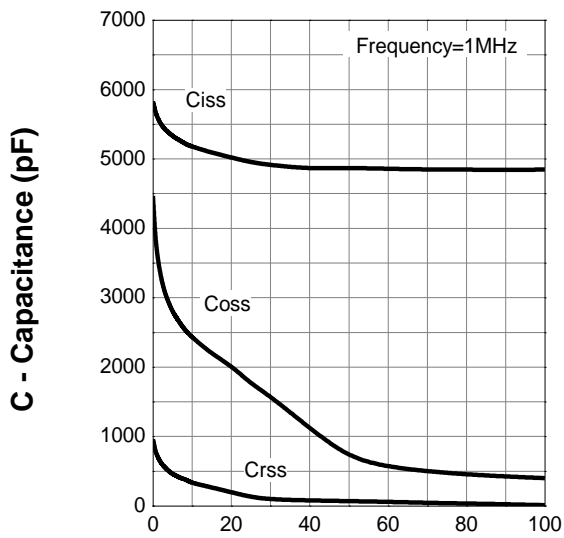
### Body Diode Characteristics



$T_j$  - Junction Temperature ( $^\circ C$ )

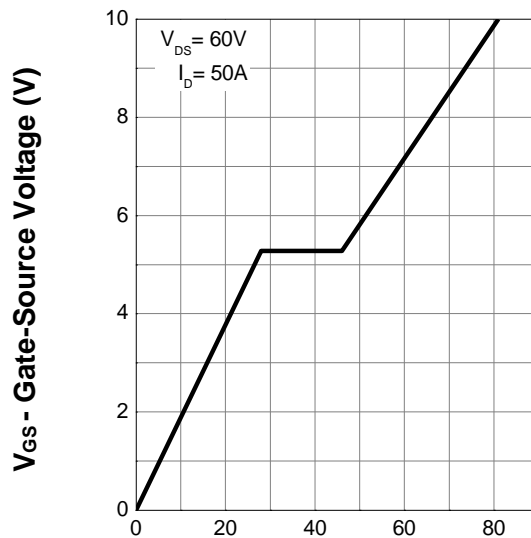
$V_{SD}$  - Source-Drain Voltage (V)

### Capacitance



$V_{DS}$  - Drain-Source Voltage (V)

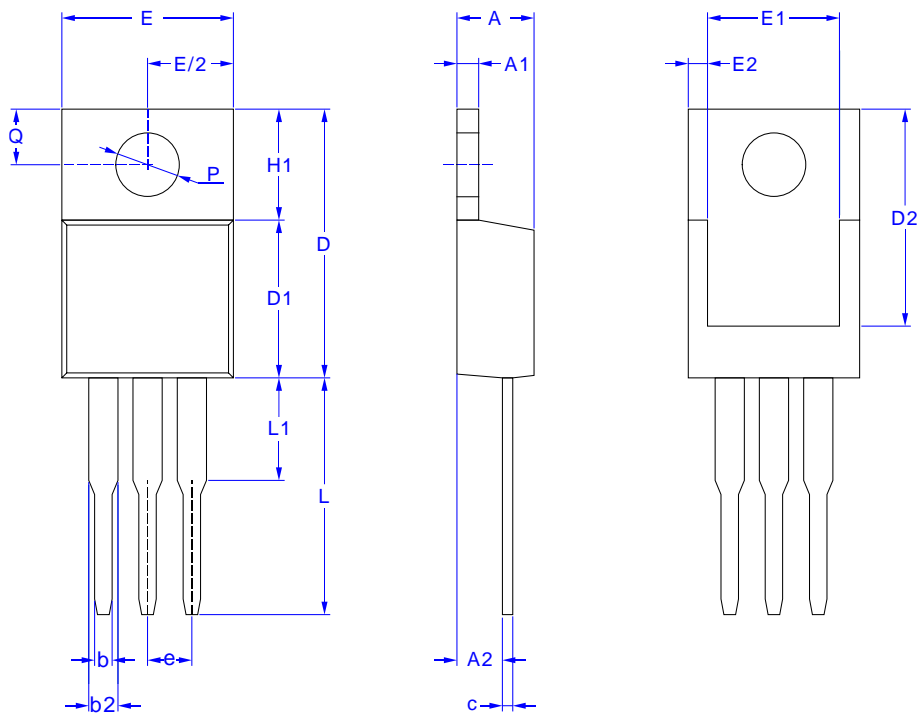
### Gate Charge



$Q_G$  - Gate Charge (nC)

## 8. Package Dimensions

### TO-220 Package



Symbol	Dimensions in Millimeter		Dimensions in Millimeter	
	MIN.	MAX.	MIN.	MAX.
A	3.56	4.83	0.140	0.190
A1	0.51	1.40	0.020	0.055
A2	2.03	2.92	0.080	0.115
b	0.38	1.02	0.015	0.040
b2	1.14	1.78	0.045	0.070
c	0.36	0.61	0.014	0.024
D	14.22	16.51	0.560	0.650
D1	8.38	9.02	0.330	0.355
D2	12.19	12.88	0.480	0.507
E	9.65	10.67	0.380	0.420
E1	6.86	8.89	0.270	0.350
E2	0.76 BSC		0.030 BSC	
e	2.54 BSC		0.100 BSC	
H1	5.84	6.86	0.230	0.270
L	12.7	14.73	0.500	0.580
L1	2.54 BSC		0.100 BSC	
P	3.53	4.09	0.139	0.161
Q	2.54	3.43	0.100	0.135